

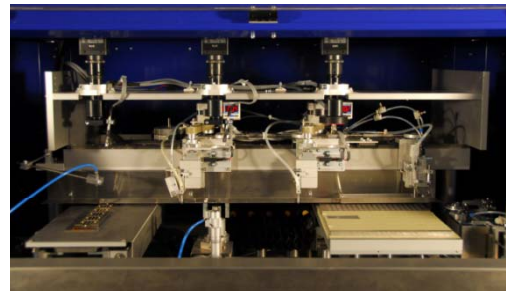
Model JFP PP420

DIE SORTER PLATFORM



APPLICATIONS:

Pick & Place
Flip Chip assembly
Very small and large component
MEMS, MMICS, ASIC, IR sensor, ...
Capa Chips, Resistor chips...
Eutectic thermo cycle
Wafer sorter up to 12"
Dispenser for epoxy & solder paste
Stamping



The JFP PP420 series is designed for all high density substrate based applications such as Matrix BGA, PBGA and many others as well as lead frame applications such as QFN/MLP. A unique maintenance free, high speed transfer head is the heart of the system that bring the UPH up to 3000 upon configuration. The PP420 series is extremely user friendly, a graphical user guide supports the user during operation with practical illustrations and reference systems. The PP420 series provide customers with the highest quality and best cost / performance system on the market. Our proven expertise in bonding application effectively provides the technology and support to help our customers.

Specifications	
Sorter	<p>Single chip multi placement Throughput: 2000p/h Placement accuracy: <20µm Die size: 250µmx250µm to 20mmx20mm Wafer size: 6" / option 8" and 12"</p>
Module PP 400	<p>High speed pick up & transfer head Length: 300 mm Pick up component detection Touch down sensor Z programmable speed Place force programmable Rotary resolution 10800 stp/resolution Rotation +/- 20 deg Low pressure puff-off controller Substrate table 100mm x 100mm global or local alignment per position</p>
Wafer Station	<p>Wafer manual loading 6" XY table wafer stroke + loading Programmable ejection system Needle holder mag Graphite chuck Z programmable</p>
Vision System	<p>Cognex PAT MAX 8000 Quality reject criteria Crosshair and pattern on display Wafer mapping Ink die detection OCR Die detection Programmable lighting oblique & vertical</p>
Software	<p>OS Windows XP pro User interface: GUI supported by expert panels Standard language : English Instrument indication integrated in the user interface</p>
Hardware	<p>PC system Key board Joystick 17" flat panel 3 x camera high resolution 1/3" matrix</p>
Options	<p>WS420-8 : 8 inches wafer WS420-12: 12 inches wafer Stamping platform Dispenser platform Eutectic platform Preform platform Fine centering platform Flip Module</p>